

Transaction Information

Tool ID	FIB2104
Tool Status	Disconnected
Location	Malta, USA
Wafer Size	300 mm
Fab Section	Lab
Tool Available Date	2022-04-18

General Product Information

Vendor Supplier	FEI
Model	FEI ExSolve CLM Next Gen
Vintage	2016
Serial No	9923609
Asset Description	FIB2104-FEI ExSolve CLM WTP(MT)&Edwards
Software Version	NA
CIM	Factory Automation Available
Process	FIB – cut samples from wafers in line

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Main System	FEI ExSolve G2 Full Wafer TEM Preparation System	1	
Handler System	Brooks Front End	1	
Factory Interface	SMIF	1	
Options System	GIS, Dep	5	
Others			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
TMC Table and Edwards XDS35 Dry Pumps	3	

Missing/Faulty Parts / Accesories List

Description	Quantity
NONE	

Tool Pictures

General

FEI ExSolve G2 Full Wafer TEM
Preparation System











5350 NE Dawson Creek Drive
Hillsboro, Oregon 97124 USA

Model:	EXSOLVE 2 WTP
Serial Number:	9923609
Year of Manufacture:	2016
Voltage:	230 VAC, 1 Phase
Wiring Configuration:	2 Wire + Ground
Frequency:	50/60 Hz
Full Load:	6 A
Largest Load:	1 A
Input Breaker:	30 A
SCCR:	2000 A
Interrupting Capacity:	2000 A
Diagram Number:	1114837



1114837

Additional Configuration Files